

Form PTO 1445 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 202450US0	SERIAL NO. 09/770,289	
LIST OF REFERENCES CITED BY APPLICANT OCT 09 2003 OCT 09 2003 PATENT & TRADEMARK OFFICE U.S. DEPARTMENT OF COMMERCE		APPLICANT Atsushi SHIOTA, et al.		FILING DATE January 29, 2001		
				GROUP 1712		
U.S. PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
MF	AA 6,207,555 B1	03/27/2001	Matthew ROSS			
MF	AB 6,548,899 B2	04/15/2003	Matthew ROSS			
MF	AC 6,271,146 B1	08/07/2001	Matthew ROSS			
MF	AD 6,582,777 B1	06/24/2003	Matthew ROSS, et al.			
MF	AE US 2003/0008481 A1	01/09/2003	Matthew ROSS, et al.			
MF	AF 6,489,225 B1	12/03/2002	Matthew ROSS, et al.			
MF	AG US 2003/0102084 A1	06/05/2003	William LIVESAY, et al.			
MF	AH 6,426,127 B1	07/30/2002	Matthew ROSS, et al.			
MF	AI 6,358,670 B1	03/19/2002	Selmer WONG, et al.			
MF	AJ 6,319,655 B1	11/20/2001	Selmer WONG, et al.			
	AK					
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	AM					
	AN					
FOREIGN PATENT DOCUMENTS						
	DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES	NO	
MF	AO JP2001015500	01/19/2001	JAPAN (English-language Abstract only)	/	/	
	AP					
	AQ					
	AR					
	AS					
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	AU					
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OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)						
MF	AW	J.J. YANG, et al., "Electron Beam Curing of Siloxane SOG for Non-etch Back Process". Advanced Metallization & Interconnect Systems for ULSI Applications in 1996: Materials Research Society Conference Proceedings. ed. Robert Havemann, et al., May 1997, pp. 505-509.				
MF	AX	J.J. YANG, et al., "Integration of Spin-on Low-k Dielectrics Using E-Beam Curing for ULSI Multilevel Interconnects". Advanced Metallization and Interconnect Systems for ULSI Applications in 1997: Materials Research Society Conference Proceedings. ed. R. Cheung, et al., March 1999, pp. 359-365.				
	AY	Applied Materials' assertion that Matthew Ross is a co-inventor of the 09/770,289 application. See discussion in Amendment filed herewith.				

Additional References sheet(s) attached

12/3/03

Confidential and Not Considered in Patentability Determination